

*Sensors and Materials*  
**Special Issue on Advanced Hardware Technology, Observation  
and Data Science Methods, and Practical Use of Remote Sensing**

**Call for Papers**

Remote sensing is a technique for acquiring information about a distant object using a sensor. Among the various remote sensing technologies, remote sensing mainly involves observing electromagnetic waves from objects on the earth's surface or in the atmosphere using sensors mounted on platforms such as artificial satellites, aircraft, and UAVs. The study of remote sensing encompasses the science and technology used to obtain information on objects in various fields, such as land environment; air environment/weather forecasting; ocean/land water environment; agriculture, forestry, and fisheries; geological survey/resource development; snow and ice environment; disaster response; surveying/civil engineering; and maritime security/defense. Remote sensing is also used in research and business and for the observation of both the earth and celestial bodies, such as the moon, planets, asteroids, and sun. For this special issue, with the purpose of clarifying the direction of future remote sensing technology, we are calling for papers on advanced hardware technology for remote sensing; observation and data science methods for extracting useful information from big data observed by remote sensing; and research on the practical use of remote sensing data to meet social needs in both emergencies and daily life. Topics of interest include, but are not limited to:

**Scope:**

Optical sensors	LiDAR
Thermal sensors	Data analysis
Microwave sensors	Integration of remote sensing data and models
Microbial sensors	Land use/land cover
Imaging sensors	Practical use of satellite aircraft and UAV data

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**Guest Editor:** Prof. Kazuo Oki (Kyoto University of Advanced Science, The University of Tokyo)

**Submit to:** Online Manuscript Submission System (<https://myukk.org/form/>)

**(Attention)**

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication (for example, JPY 112200 for 10 pages in *Sensors and Materials* format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors should bear the proofreading fee (JPY 10000–40000), which will be charged with the publication fee.

If you have any questions, please feel free to contact the editorial staff at the address below.

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